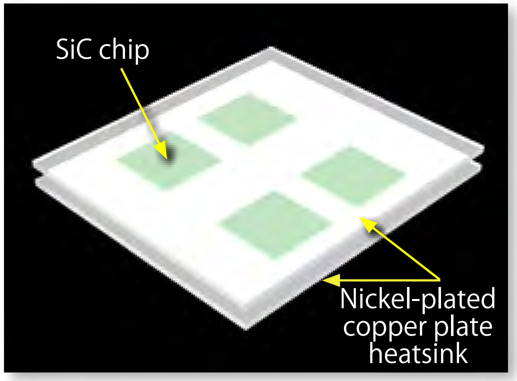
SoundPower for Space

SoundBonding application

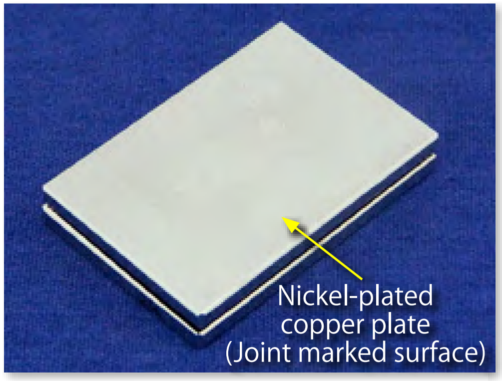
ECB

〈The both sides die-bonding of SiC chips and heatsinks〉

(Patents pending)



Inside image of both sides die-bonding structure



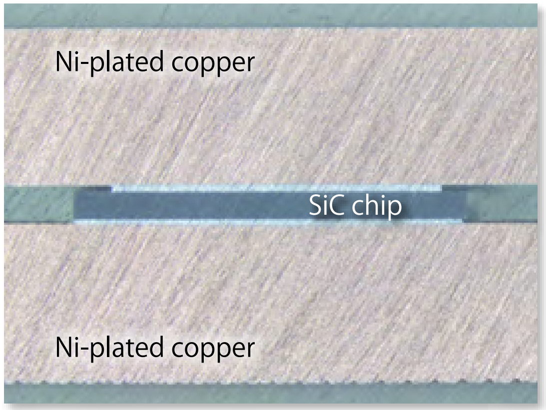
After both sides die-bonding by sound

[SiC package]
Both sides die-bonding of four SiC chips between two Ni-plated copper plates

3DB DMBonding
Different Materials Bonding

★[3DB & DMB] by stacked different materials
★Die-bonding of four SiC chips and nickel-plated copper heatsinks
★Bonding by sound energy only, no need of bond and metal paste with heat
★ Cleared heat shock test（−50 ～ 600℃）
★ Bonding at room temperature in atmosphere
★ Supplied energy is electricity and air only
★ Bonding on desktop

Example observation
Both sides die-bonding cross section



Enlarged bonding part

SoundPower® Laboratory

ULTEX®